

ASO ONLY (APPLICATION SPECIFIC ORDER)

QTH-XXX-01-X-D-EMX-XX

No OF POSITIONS
-030, -060, -090,
N **120, **150
(PER ROW)
N **SEE NOTE 13

OPTION
-TY: TRAY PACKAGING

EDGE MOUNT THICKNESS
-EM2: .064[1.63] +/- .004 PCB
(USE QTH-30-01-D-EM2-XX &
T-1S42-01-X)

-EM3:
(USE QTH-30-01-D-EM3-XX &
T-1S42-02-X)

SEE NOTE 12

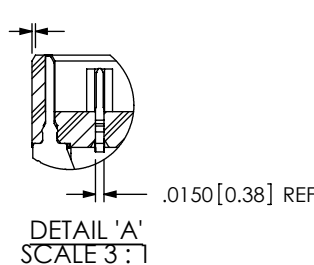
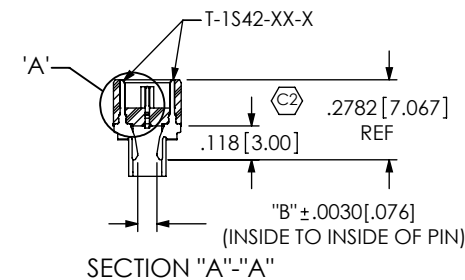
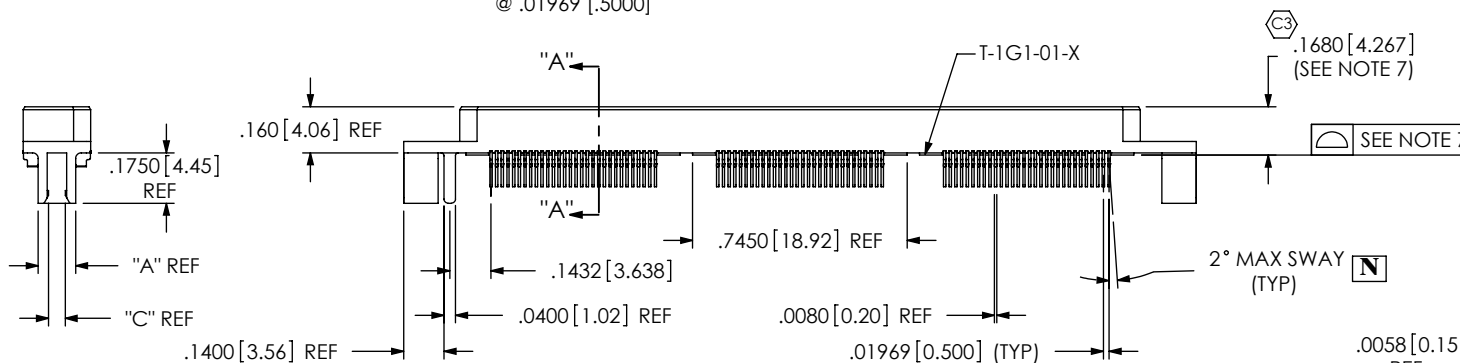
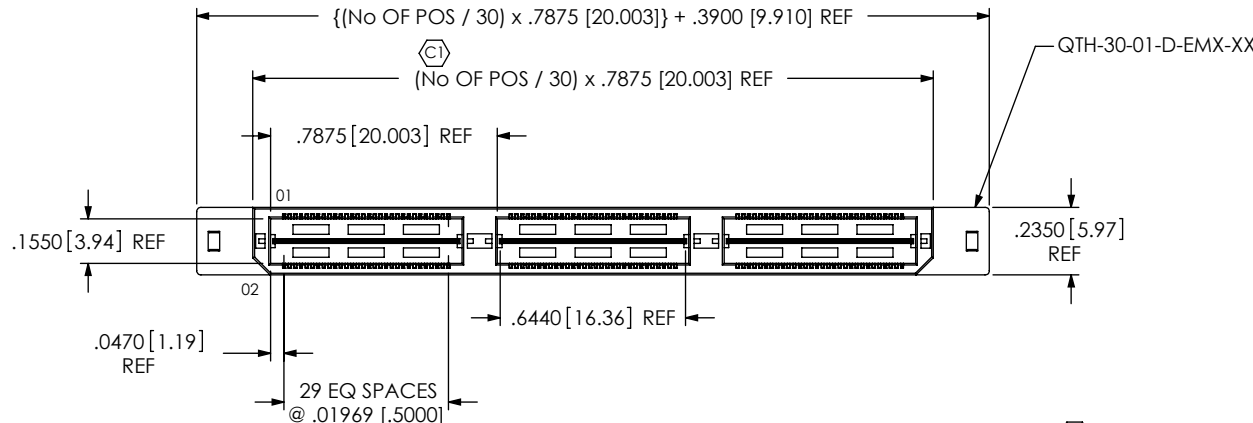
ROW SPECIFICATION
-D: DOUBLE
(USE QTH-30-01-D-EMX-XX)

PLATING SPECIFICATION No OF BANKS
-F: FLASH SELECTIVE GOLD WITH MATTE TIN TAILS
(USE T-1S42-XX-F & T-1G1-01-F) [SEE NOTE 8]
-L: LIGHT SELECTIVE GOLD WITH MATTE TIN TAILS
(USE T-1S42-XX-L & T-1G1-01-L)
-H: HEAVY GOLD
(USE T-1S42-XX-H & T-1G1-01-G)
-C: ELECTRO-POLISHED SELECTIVE
(USE T-1S42-XX-C, T-1G1-01-L)

TABLE 1					
EDGE MOUNT	"A"	"B"	"C"	BODY	CONTACT
-EM2	.130[3.30]	.0670[1.702]	.058[1.47]	QTH-30-01-D-EM2-XX	T-1S42-01-X
*-EM3	.160[4.06]	.0980[2.489]	.088[2.24]	QTH-30-01-D-EM3-XX	T-1S42-02-X

* = SEE NOTE 12

DO NOT
SCALE FROM
THIS PRINT



NOTES:

1. \odot REPRESENTS A CRITICAL DIMENSION.
2. BURR ALLOWANCE: .0015[.038] MAX.
3. MINIMUM PUSHOUT FORCE: 5 OZ.
4. MINIMUM GROUND PLANE RETENTION: 1 LB.
5. NOTE DELETED.
6. PARTS TO BE MOLDED TO POSITION.
7. GROUND PLANE TO BE WITHIN .004[.10] COPLANARITY & MAX VARIANCE OF .002.
8. -L PLATING CAN BE SUBSTITUTED FOR -F PLATING (TERMINAL),
-G PLATING CAN BE SUBSTITUTED FOR -F PLATING (GROUND PLANE).
9. NOTE DELETED.
10. BOARD THICKNESS TO BE MEASURED FROM SOLDER PAD TO SOLDER PAD.
11. SEE www.samtec.com/processing/edgemt_tectalk/index.htm FOR PROCESSING EDGE MOUNT PARTS TO BOARD.
12. -EM3 IS NOT A STANDARD OFFERING; AVAILABLE AS AN ASP ONLY. PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP WITH ORDER INQUIRIES
13. FOR NEW APPLICATIONS REQUIRING THESE POSITIONS, PLEASE CONTACT SAMTEC INTERCONNECT PROCESSING GROUP.

TABLE 2	
No OF POSITIONS	MAX BOW
-030, -060, -090	.004 [.10]
-120, -150	.006 [.15]

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN INCHES.
TOLERANCES ARE:
DECIMALS ANGLES
.XX: ±.01[.3]
.XXX: ±.005[.13]
.XXXX: ±.0020[.051]

PROPRIETARY NOTE
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PURPOSE OTHER THAN THAT WHICH IT WAS
OBTAINED WITHOUT THE EXPRESSED WRITTEN
CONSENT OF SAMTEC, INC.

MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 1.5:1
INSULATOR: LCP, COLOR: BLACK
TERMINAL & GROUND PLANE: PHOS BRONZE

DESCRIPTION:
.5mm HS EDGE MOUNT TERMINAL ASSEMBLY
DWG. NO.
QTH-XXX-01-X-D-EMX-XX

BY: DEAN P 4/20/2000 SHEET 1 OF 1

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